

PCN Number:	20140605000		PCN Date:	06/13/2014	
Title:	Qualification of TI Clark and NSE as Additional Assembly and Test Site for Select Devices				
Customer Contact:	PCN Manager	Phone:	+1(214)480-6037	Dept:	Quality Services
Proposed 1st Ship Date:	09/13/2014	Estimated Sample Availability:	Date Provided at Sample request		
Change Type:					
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>	Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/>	Wafer Fab Materials
				<input type="checkbox"/>	Wafer Fab Process
PCN Details					
Description of Change:					
<p>Texas Instruments Incorporated is announcing the qualification of TI Clark and NSE as additional assembly/test site for select devices listed in the "Product Affected" Section. Current assembly sites are as follows and no material differences between assembly sites.</p> <ul style="list-style-type: none"> • Group 1 Device: TI Malaysia to TI Clark • Group 2 Device: TI Clark to NSE <p>Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.</p>					
Reason for Change:					
Continuity of supply.					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					

Changes to product identification resulting from this PCN:

Group 1 Device: TI Malaysia to TI Clark

Assembly Site		
TI Malaysia	Assembly Site Origin (22L)	ASO: MLA
TI Clark	Assembly Site Origin (22L)	ASO: QAB

ASSEMBLY SITE CODES: TI Malaysia = K , TI-Clark = I

Group 2 Device: TI Clark to NSE

Assembly Site		
TI Clark - Philippines	Assembly Site Origin (22L)	ASO: QAB
NSE Thailand	Assembly Site Origin (22L)	ASO: NSE

ASSEMBLY SITE CODES: TI CLARK =I, NSE = J

Sample product shipping label (not actual product label)

Product Affected: Group 1 Device (TI Malaysia to TI Clark)

TPS51206DSQR	TPS51206DSQR-P	TPS51206DSQT
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Product Affected: Group 2 Device (TI Clark to NSE)

PCM3070IRHBR	PCM3070IRHBT	TLV320AIC3204IRHBR	TLV320AIC3204IRHBT
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Qualification Data : Group 1

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.

Qual Vehicle : TPS51206DSQ (MSL2-260C)

Package Construction Details

Assembly Site:	TI Clark	Mold Compound:	4208625
# Pins-Designator, Family:	10-DSQ, WSON	Mount Compound:	4207768
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu

Qualification: Plan Test Results

Reliability Test	Conditions	Sample Size/Fail
Manufacturability	(per mfg. Site specification)	Pass

Reference Qualification Data

Qual Vehicle : TPS51518RUKR (MSL2-260C)				
Package Construction Details				
Assembly Site:	TI Clark	Mold Compound:	4208625	
# Pins-Designator, Family:	20-RUK, WQFN	Mount Compound:	4207768	
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	0.96 Mil Dia., Cu	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
Electrical Characterization	-	30/0	-	-
**Life Test	170C (420 Hrs)	77/0	77/0	77/0
**Biased HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**High-Temp Storage Bake	170C (420 Hrs)	77/0	77/0	77/0
**Temp Cycle	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Moisture Sensitivity	Level 2-260C	12/0	12/0	12/0
Manufacturability	(per mfg. Site specification)	Pass	-	-
Notes ** - Preconditioning sequence: Level 2-260C.				

Qualification Data : Group 2

This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.				
Qual Vehicle : SN0509043RGC (MSL3-260C)				
Package Construction Details				
Assembly Site:	NSE	Mold Compound:	CZ0134	
# Pins-Designator, Family:	64-RGC, VQFN	Mount Compound:	PZ0031	
Lead frame (Finish, Base):	NiPdAu, Cu	Bond Wire:	2.0 Mil Dia., Au	
Qualification: <input type="checkbox"/> Plan <input checked="" type="checkbox"/> Test Results				
Reliability Test	Conditions	Sample Size/Fail		
		Lot#1	Lot#2	Lot#3
Electrical Characterization	-	Pass	Pass	Pass
**Life Test	140C (480 Hrs)	113/0	116/0	116/0
**HAST	130C/85%RH (96 Hrs)	77/0	77/0	77/0
**Autoclave	121C, 15 PSIG, 29.7 PSIA (96 Hrs)	77/0	77/0	77/0
**Thermal Shock	-65C/+150C (1000 Cyc)	77/0	77/0	77/0
**High-Temp Storage	170C (420 Hrs)	77/0	77/0	77/0
**Temp Cycle	-65C/+150C (500 Cyc)	77/0	77/0	77/0
Solderability	8 Hrs Steam Age	22/0	22/0	22/0
Salt Atmosphere	24 Hrs	22/0	22/0	22/0
X-ray	(top side only)	5/0	5/0	5/0
Manufacturability	(per mfg. Site specification)	Pass	Pass	Pass
Notes ** - Preconditioning sequence: Level 3-260C.				

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com